1. FURTHER INFORMATION ABOUT OUR GROUP

Incorporation

The predecessor of our Company, Jiangsu Silicon Integrity Semiconductor Technology Ltd.* (江蘇芯德半導體科技有限公司) was established in the PRC on on September 11, 2020 with limited liability. On June 27, 2024, our Company was converted from a limited liability company into a joint stock limited liability company in accordance with applicable PRC laws and regulations and renamed as Jiangsu Silicon Integrity Semiconductor Technology Co., Ltd. (江蘇芯德半導體科技股份有限公司). Our registered office is located at No. 8 Linchun Road, Pukou Economic Development Zone, Pukou District, Nanjing, PRC.

We have established a place of business in Hong Kong at 31/F, Tower Two, Times Square, 1 Matheson Street, Causeway Bay, Hong Kong and were registered with the Registrar of Companies in Hong Kong as a non-Hong Kong company under Part 16 of the Companies Ordinance on October 24, 2025. Ms. Ye Jiahong (葉嘉紅) of TMF Hong Kong Limited has been appointed as the authorized representative of our Company for the acceptance of service of process and notices on behalf of our Company in Hong Kong. The address for service of process on our Company in Hong Kong is the same as our principal place of business in Hong Kong as set out above.

As our Company was established in the PRC, we are subject to relevant laws and regulations of the PRC. A summary of the relevant aspects of laws and regulations of the PRC and our Articles of Association is set out in “Regulations” and Appendix V to this document, respectively.

Changes in Share Capital of Our Company

Save as disclosed in “History, Development and Corporate Structure”, there has been no alteration in the share capital of our Company within two years immediately preceding the date of this Document.

Changes in Share Capital of Our Subsidiary

Our subsidiary is set out in the Accountants’ Report, see “Appendix I — Accountants’ Report”. Save for the subsidiary mentioned in “Appendix I — Accountants’ Report”, our Company has no other subsidiary. Save as disclosed above and in “History, Development and Corporate Structure”, there are no other alteration in registered capital of our subsidiary within the two years immediately preceding the date of this document.

Resolutions Passed by Our Shareholders

At the extraordinary general meeting of our Company held on October 13, 2025, among other things, the following resolutions were passed by the Shareholders:

(i) the [**REDACTED**] of H Shares with a nominal value of RMB1.00 each and the [**REDACTED**] of such H Shares on the Stock Exchange;

(ii) the number of H Shares to be [**REDACTED**] pursuant to the [**REDACTED**], and the grant to the [**REDACTED**] (or their representatives) of the [**REDACTED**] of not more than [**REDACTED**] of the number of H Shares [**REDACTED**] pursuant to the [**REDACTED**];

(iii) subject to the completion of filing with the CSRC, upon completion of the [**REDACTED**], [**REDACTED**] Unlisted Shares in aggregate held by our Shareholders will be [**REDACTED**] into H Shares on a one-for-one basis;

(iv) subject to the completion of the [**REDACTED**], the Articles of Association have been approved and adopted, which shall become effective on the [**REDACTED**], and our Board has been authorized to amend the Articles of Association to the extent necessary in accordance with any comments from the relevant regulatory authorities; and

(v) approving the Board and person(s) authorized by the Board to handle all matters relating to, among other things, the [**REDACTED**] and the [**REDACTED**] of H Shares on the Stock Exchange.

Reorganization

We have not gone through any corporate reorganization for the purpose of the [**REDACTED**]. For details of the history and development of our Company, see "History, Development and Corporate Structure."

2. FURTHER INFORMATION ABOUT OUR BUSINESS

Summary of our Material Contract

We have entered into the following contract (not being a contract entered into in the ordinary course of business) within two years immediately preceding the date of this document that are or may be material:

(i) the [**REDACTED**].

Intellectual Property Rights

Trademarks

As of the Latest Practicable Date, our Group has registered the following trademarks which we consider to be or may be material to our business:

Trademark	Place of Registration	Registration No.	Class	Expiration Date
CAPiC	PRC	70402212	40	September 20, 2033
CAPiC	PRC	70095085	40	August 27, 2033
芯德	PRC	70098973	40	August 27, 2033
XD-HPFO	PRC	60091353	40	May 6, 2032
XD-HPFO	PRC	60099046	42	April 27, 2032
XD-HPFO	PRC	60085397	9	May 6, 2032
JSSISEMI	PRC	59650278	40	March 20, 2032
	PRC	59645130	40	March 13, 2032
JSSISEMI	PRC	50824487	42	August 6, 2031
JSSISEMI	PRC	50847303	9	July 6, 2031
	PRC	50828235	42	August 20, 2031
	PRC	50643245	9	October 6, 2031
JSSI semi 芯德半导体	Hong Kong	307018353	9, 35, 40, 42	September 3, 2035

Domain Names

As of the Latest Practicable Date, we have registered or been authorized to use the following domain names which we consider to be material in relation to our business:

Domain Name	Registered Owner	Expiry Date
jssisemi.com.cn	Company	January 27, 2033
jssisemi.com	Company	September 28, 2032
jssisemi.cn	Company	November 4, 2032

Copyrights

As of the Latest Practicable Date, our Group has registered the following copyrights which we consider to be or may be material to our business:

Copyright Name	Place of Registration	Registration No.	Date of first publication
Onboarding Assessment Management System (上崗考核管理系統)	PRC	2023SR0743250	June 28, 2023
WMS (Warehouse Management System) (WMS倉庫管理系統)	PRC	2023SR0421217	March 30, 2023
Abnormality Detection and Classification System (異常偵測與分類系統)	PRC	2022SR1341662	September 2, 2022
Statistical Process Control (SPC) System (統計過程控制系統)	PRC	2021SR1591735	October 29, 2021
Quality Abnormality Handling System (品質異常處理系統)	PRC	2021SR1553839	October 25, 2021
Photomask Management System (光罩掩膜版管理系統)	PRC	2021SR1532382	October 20, 2021
Electronic Maintenance System (電子化保養系統)	PRC	2021SR1534638	October 20, 2021
Equipment Automation Operation Control System (設備自動化作業控制系統)	PRC	2021SR1342437	September 8, 2021
Xinde Equipment Program Management System (芯德設備程序管理系統)	PRC	2021SR0881304	June 11, 2021

Patents

As of the Latest Practicable Date, our Group has registered the following patents which we consider to be or may be material to our business:

Patent	Place of Registration	Application Number	Owner	Type	Application Date
A Heating Strip Tightening Device for a Vacuum Packaging Machine (一種真空包裝機的加熱條收緊裝置) . .	PRC	CN202422227269.5	Company	Utility Model	September 11, 2024
A Double-sided Packaging Hybrid Chip Structure of a Through-hole Substrate (一種通孔基板的雙面封裝混合芯片結構)	PRC	CN202422489687.1	Company	Utility Model	October 15, 2024
A Flip-chip Adsorption Device (一種倒裝芯片吸附裝置)	PRC	CN202422232500.X	Company	Utility Model	September 12, 2024
A Flip-chip Packaging Structure with Attached Heat Dissipation Cap (一種貼散熱蓋的倒裝芯片封裝結構)	PRC	CN202422356795.1	Company	Utility Model	September 26, 2024
A High-density Stacked Packaging Structure Integrating Capacitor and PMIC Chip, and Its Packaging Method (一種集成電容與PMIC芯片的高密度堆疊封裝結構及封裝方法)	PRC	CN202510652690.7	Company	Invention Patent	May 21, 2025
A Packaging Structure of a Filter Module and Its Manufacturing Method (一種濾波器模組的封裝結構及其製造方法) . . .	PRC	CN202211122369.0	Company	Invention Patent	September 15, 2022
An Automatic Positioning Cassette Dimension Platform Device (一種自動定位片匣尺寸平台裝置)	PRC	CN202422389076.X	Company	Utility Model	September 29, 2024
A Wafer Positioning Jig (一種晶圓定位治具) . .	PRC	CN202420650159.7	Company	Utility Model	April 01, 2024
A Semiconductor Packaging Structure with Dual Package Bodies (一種具有雙封裝體的半導體封裝結構)	PRC	CN202422721183.8	Company	Utility Model	November 08, 2024

Patent	Place of Registration	Application Number	Owner	Type	Application Date
A Circuit Control Chip Packaging Structure (一種電路控制芯片封裝結構)	PRC	CN202422150192.6	Company	Utility Model	September 02, 2024
A Method to Prevent Delamination in Embedded Chip-level Ball Grid Array Bonding Process (一種嵌入式晶片級球柵陣列鍵合工藝中避免分層的方法)	PRC	CN202510541161.X	Company	Invention Patent	April 28, 2025
An Ultra-narrow Pitch PI Layer Opening Method and Semiconductor Packaging Structure (一種超窄間距PI層開口方法及半導體封裝結構)	PRC	CN202210549652.5	Company	Invention Patent	May 20, 2022
A Jig for Measuring the Height of Wafer Stage and Probe Cap (一種測量晶圓工作台與頂針帽高度的治具)	PRC	CN202422222993.9	Company	Utility Model	September 10, 2024
An Automated Wiring Drawing Design Software System and Design Method (一種佈線圖紙設計自動化軟件系統及設計方法)	PRC	CN202111663523.0	Company	Invention Patent	December 30, 2021
A Jig for Comprehensive Inspection of Semiconductor Packaging Products (一種全方位檢測半導體封裝產品的治具)	PRC	CN202421662953.X	Company	Utility Model	July 12, 2024
A Movable Material Hopper for Heat Dissipation Cap (一種散熱蓋活動料倉)	PRC	CN202421843754.9	Company	Utility Model	July 31, 2024
A Portable Chip Transport Basket (一種便攜式芯片運輸提籃)	PRC	CN202421750611.3	Company	Utility Model	July 23, 2024
A Bump Height Measurement Method for Wafer Surface with Re-passivation Layer (一種晶圓表面具有再鈍化層的凸塊高度測量方法)	PRC	CN202211695534.1	Company	Invention Patent	December 28, 2022

Patent	Place of Registration	Application Number	Owner	Type	Application Date
A Fan-out Type Chip Packaging Structure (一種扇出型芯片封裝結構).	PRC	CN202420814100.7	Company	Utility Model	April 18, 2024
An Ultra-thin Chip Carrier and Its Chip Packaging Structure and Packaging Method (一種芯片超薄封裝載板及芯片封裝結構和芯片封裝方法)	PRC	CN202210485627.5	Company	Invention Patent	May 06, 2022
A Device for Fixing Adhesive Film on a Mounting Ring (一種對貼片環固定膠膜的裝置).	PRC	CN202420650143.6	Company	Utility Model	April 01, 2024
A Chip Structure and Its Bare Chip Packaging Structure for Improving Glue Overflow (一種改善溢膠的芯片結構及其裸露芯片封裝結構) . . .	PRC	CN202420321053.2	Company	Utility Model	February 20, 2024
An Automatic Clamping Device for Electroplating Wire Conductive Blocks (一種電鍍線導電塊自動夾緊裝置)	PRC	CN202421398686.X	Company	Utility Model	June 19, 2024
A TCB Porous Placement Tool (一種TCB多孔放置工具)	PRC	CN202421371175.9	Company	Utility Model	June 17, 2024
A Front-side Protected Wafer-level Chip Packaging Structure (一種正面保護的晶圓級芯片封裝結構).	PRC	CN202420816705.X	Company	Utility Model	April 18, 2024
A Chip Packaging Structure (一種芯片封裝結構)	PRC	CN202421242815.6	Company	Utility Model	June 03, 2024
A Guide Post for Electroplating Machine Chuck (一種電鍍機卡盤導向柱)	PRC	CN202420501114.3	Company	Utility Model	March 15, 2024
A Chip Stacked Packaging Structure (一種芯片疊層封裝結構). .	PRC	CN202420494637.X	Company	Utility Model	March 14, 2024
A Chip Suction Nozzle and Its Comprising Chip Soldering Device (一種芯片吸嘴及其組成的芯片焊接裝置)	PRC	CN202420485417.0	Company	Utility Model	March 13, 2024

Patent	Place of Registration	Application Number	Owner	Type	Application Date
A Drop-resistant Material Device and Its Comprising Wire Bonding Machine (一種防摔料裝置及其組成的連線機)	PRC	CN202323367008.5	Company	Utility Model	December 11, 2023
A Wire Bonding Machine Quick Cooling Device (一種焊線機台快速冷卻裝置)	PRC	CN202421058949.2	Company	Utility Model	May 15, 2024
A Packaging Structure Enhancing Heat Dissipation of Flip-chip Square Flat No-lead Products (一種提高倒裝方形扁平無引腳封裝產品散熱性的封裝結構)	PRC	CN202420002729.1	Company	Utility Model	January 02, 2024
A Silver-plated Frame to Prevent Die-attached Glue Overflow and Its Comprising Packaging Structure (一種防止晶粒黏貼膠溢出的鍍銀框架及其組成的封裝結構)	PRC	CN202420036907.2	Company	Utility Model	January 08, 2024
A Single-chip Product Carrier Positioning and Inspection Device (一種單顆芯片產品載具定位檢測裝置)	PRC	CN202421150985.1	Company	Utility Model	May 24, 2024
An Automatic Magazine Inspection Device (一種自動檢驗彈夾裝置)	PRC	CN202420300156.0	Company	Utility Model	February 19, 2024
A Heating Platform Device Suitable for Bottom Fill (一種適用於底部填充的加熱平台裝置)	PRC	CN202420188709.8	Company	Utility Model	January 26, 2024
An Ultrasonic Scanning Carrier Stage and Focal Length Quick Determination Method (一種超聲波掃描載具台及焦距快速確定方法)	PRC	CN202211131176.1	Company	Invention Patent	September 16, 2022
A Chip Stacking Structure with Dual Wiring Layers (一種包含雙重佈線層的芯片堆疊結構)	PRC	CN202421054470.1	Company	Utility Model	May 15, 2024

Patent	Place of Registration	Application Number	Owner	Type	Application Date
A Fan-out Wafer-level Packaging Structure for MEMS Chip Interconnection (一種實現MEMS芯片互聯的扇出型晶圓級封裝結構)	PRC	CN202421024469.4	Company	Utility Model	May 11, 2024
A Photolithography Plate Protective Film Application Jig (一種光刻版保護膜貼膜治具)	PRC	CN202420754611.4	Company	Utility Model	April 12, 2024
A Material Jam Prevention Device for Sorting Machine (一種分選機防卡料裝置)	PRC	CN202323529869.9	Company	Utility Model	December 25, 2023
A Ring Silver-plated Frame Improving Die-attached Film Delamination (一種改善晶粒黏貼膜分層的環鍍銀框架)	PRC	CN202323529848.7	Company	Utility Model	December 25, 2023
A Sputtering Process Stability Evaluation Method (一種濺射工藝穩定性評估方法)	PRC	CN202211696268.4	Company	Invention Patent	December 28, 2022
A UV Film Scoring Device (一種UV膜劃膜裝置)	PRC	CN202420821820.6	Company	Utility Model	April 19, 2024
An Arc-prevention Device for Plasma Cleaning Machines (適用於等離子清洗機的防電弧產生裝置)	PRC	CN202420565134.7	Company	Utility Model	March 22, 2024
A Fan-out Packaging Method and Fan-out Packaging Structure (一種扇出型封裝方法及扇出型封裝結構)	PRC	CN202111358610.5	Company	Invention Patent	November 16, 2021
An Automatic Cleaning Device for Flip-chip Machine Steel Nozzles (一種倒裝機鋼嘴頭的自動清潔裝置)	PRC	CN202420050924.1	Company	Utility Model	January 09, 2024
A Reflow Oven Capable of Preventing Misalignment (一種能夠預防回流偏移的回流機)	PRC	CN202323575466.8	Company	Utility Model	December 27, 2023
A Quick Coordinate Tray Identification Device (一種快速識別坐標託盤)	PRC	CN202420772165.X	Company	Utility Model	April 15, 2024

Patent	Place of Registration	Application Number	Owner	Type	Application Date
A Packaging Structure for Reducing Thickness of Flip-chip Products (減薄倒裝產品厚度的封裝結構)	PRC	CN202322628825.5	Company	Utility Model	September 26, 2023
A Wafer Cutting Blade (一種晶圓切割刀片)	PRC	CN202420501123.2	Company	Utility Model	March 15, 2024
A Hanging-type Electroplating Machine Cleaning Tank (一種掛鍍式電鍍機清洗槽)	PRC	CN202420378456.0	Company	Utility Model	February 29, 2024
An Adaptive Multi-thickness Plastic Encapsulation Mold (一種自適應多種厚度塑封模具)	PRC	CN202420334682.9	Company	Utility Model	February 23, 2024
A Heat Dissipation Cap Enhancing FCBGA Packaging Flatness and Its Comprising Packaging Structure (一種提高FCBGA封裝平整度的散熱蓋及其組成的封裝結構)	PRC	CN202323459970.1	Company	Utility Model	December 19, 2023
A Heat Dissipation Cap Capable of Improving Packaging Flatness (一種能夠提高封裝平整度的散熱蓋)	PRC	CN202323327111.7	Company	Utility Model	December 07, 2023
A Pickup Nozzle Link for Ultra-thin Chip Tape-and-reel Application (一種應用於超薄芯片編帶的撿取吸嘴連桿)	PRC	CN202420019775.2	Company	Utility Model	January 04, 2024
A Packaging Structure and Packaging Method with Heat Dissipation and Electromagnetic Shielding Functions (一種具有散熱和電磁屏蔽功能的封裝結構及封裝方法)	PRC	CN202411018538.5	Company	Invention Patent	July 29, 2024
A Frame for Flip-chip Packaging Structure and Its Chip Packaging Structure (一種倒裝芯片封裝結構用框架及其芯片封裝結構)	PRC	CN202323499007.6	Company	Utility Model	December 21, 2023

Patent	Place of Registration	Application Number	Owner	Type	Application Date
An Extra-large Heat Dissipation Cap and Semiconductor Packaging Structure Using the Cap (一種超大尺寸的散熱蓋及使用散熱蓋的半導體封裝結構)	PRC	CN202323393783.8	Company	Utility Model	December 12, 2023
A Vertical Mixed Chip Packaging Structure (一種垂直混裝芯片封裝結構)	PRC	CN202323494085.7	Company	Utility Model	December 21, 2023
A Packaging Structure Containing High, Medium, and Low-density Chips (一種含高中低密度芯片的封裝結構)	PRC	CN202323299000.X	Company	Utility Model	December 04, 2023
A Novel Substrate Vacuum Pad (一種新型基板真空墊塊)	PRC	CN202323171190.7	Company	Utility Model	November 23, 2023
A Packaging Structure with Electromagnetic Shielding Function (具有電磁屏蔽功能的封裝結構)	PRC	CN202322979032.8	Company	Utility Model	November 03, 2023
A Novel Glue Weight Measuring Cup (一種新型測量膠重量杯)	PRC	CN202323010782.0	Company	Utility Model	November 08, 2023
A CVS Analyzer Liquid Addition Device (一種CVS分析儀加液裝置)	PRC	CN202322933567.1	Company	Utility Model	October 31, 2023
A Filtering Device for Wafer Cleaning Applications (一種應用於晶圓清洗的過濾裝置)	PRC	CN202322892332.2	Company	Utility Model	October 26, 2023
A Substrate-free High-density Packaging Structure (無基板高密度封裝結構)	PRC	CN202322551223.4	Company	Utility Model	September 19, 2023
A Wafer, Chip, and Semiconductor Packaging Structure with Electromagnetic Shielding (具有電磁屏蔽結構的晶圓、芯片以及半導體封裝結構)	PRC	CN202322982058.8	Company	Utility Model	November 03, 2023

Patent	Place of Registration	Application Number	Owner	Type	Application Date
A QFN Product Automatic Film Stripping Device for Injection Molding Machine (一種QFN產品注塑機台自動脫膜裝置).	PRC	CN202323272285.8	Company	Utility Model	December 01, 2023
A Device for Even Distribution of Powder Resin in Injection Molding Equipment (一種讓注塑設備粉末樹脂均勻鋪撒的裝置)	PRC	CN202322933466.4	Company	Utility Model	October 31, 2023
A Cooling Device Suitable for Test Boards on Test Machines (一種適用於測試機上測試板的降溫裝置).	PRC	CN202322895174.6	Company	Utility Model	October 27, 2023
A Photoelectric Sensor Packaging Structure and Preparation Method (光電傳感器封裝結構及其製備方法)	PRC	CN202310716516.5	Company	Invention Patent	June 16, 2023
A Pentagon Adjuster Device for Calibrating Flat-edge Wafers (一種可實現平邊晶圓校準的五角調整器裝置)	PRC	CN202322768471.4	Company	Utility Model	October 16, 2023
A Face-to-face Chip Packaging Structure with High Copper Pillar Stack (一種高銅柱堆疊的面對面芯片封裝結構).	PRC	CN202322982231.4	Company	Utility Model	November 03, 2023
A Flip-chip Backside Redistribution Packaging Structure (一種倒裝芯片背面重佈線封裝結構)	PRC	CN202323025109.4	Company	Utility Model	November 09, 2023
A Method for Automatically Controlling Defective Chips on Wafer Maps (一種自動卡控晶圓圖譜上缺陷芯片的方法) . . .	PRC	CN202410268468.2	Company	Invention Patent	March 11, 2024
A Chip Encapsulation Mold and Its Secondary Encapsulation Process (一種芯片塑封模具及其二次塑封工藝方法) . . .	PRC	CN202111372272.0	Company	Invention Patent	November 18, 2021

Patent	Place of Registration	Application Number	Owner	Type	Application Date
A Dual-target Magnetron Sputtering Reaction Chamber (一種雙靶材磁控濺射反應腔室)	PRC	CN202322668547.6	Company	Utility Model	September 28, 2023
A Microscope Limiting Device (一種顯微鏡限位裝置)	PRC	CN202322599959.9	Company	Utility Model	September 25, 2023
A Potentiometric Titrator Electrode Fixing Device (一種電位滴定儀電極固定裝置)	PRC	CN202322436459.3	Company	Utility Model	September 08, 2023
A Flip-chip Defective Solder Detection Device (一種倒裝產品虛焊的檢測裝置)	PRC	CN202322245390.6	Company	Utility Model	August 21, 2023
A Universal Tray for Laser Printing Equipment (一種激光打印設備託盤通用載具)	PRC	CN202322565333.6	Company	Utility Model	September 21, 2023
A Wafer Cleaning Chamber Preventing Wafer Fly-off (一種防晶圓甩飛的清洗腔)	PRC	CN202322418482.X	Company	Utility Model	September 06, 2023
A Multi-die High-density Packaging Structure (多芯粒高密度封裝結構)	PRC	CN202322272707.5	Company	Utility Model	August 23, 2023
A Release Film (一種離型膜)	PRC	CN202321124902.7	Company	Utility Model	May 09, 2023
A Wafer-level Ultra-thin Quad Flat No-lead Chip Packaging Method and Chip Packaging Structure (一種晶圓級超薄四邊無引腳芯片封裝方法及芯片封裝結構)	PRC	CN202311528044.7	Company	Invention Patent	November 16, 2023
An Automatic Batch Device for Electroplating Line Loading and Unloading (適用於電鍍線自動上下料的自動分批裝置)	PRC	CN202322211007.5	Company	Utility Model	August 17, 2023
A Substrate Baking Fixing Device (一種基板烘烤固定裝置)	PRC	CN202322047551.0	Company	Utility Model	August 01, 2023
A Device for Quickly Inspecting the Water Pipe Status of a Dicing Saw Blade Holder (一種可供劃片設備快速檢測刀架水管狀態的裝置)	PRC	CN202321296802.2	Company	Utility Model	May 26, 2023

Patent	Place of Registration	Application Number	Owner	Type	Application Date
A Wafer-level Fan-out Packaging Structure with Heterogeneous Adhesive and Its Packaging Method (一種具有異質膠材的晶圓級扇出型封裝結構及其封裝方法)	PRC	CN202311316007.X	Company	Invention Patent	October 12, 2023
A Cutting Method for Silicon Substrate Gallium Nitride Wafers (一種矽襯底氮化鎵晶圓的切割方法)	PRC	CN202311294713.9	Company	Invention Patent	October 09, 2023
A Method and System for Merging and Distributing Maps of Multiple Chips on a Wafer (一種晶圓中多種芯片的圖譜合併、分發方法及系統)	PRC	CN202311316332.6	Company	Invention Patent	October 12, 2023
A Cutting Blade for Wettable Flank Products (一種應用於可潤濕側翼產品的切割刀片)	PRC	CN202321530807.7	Company	Utility Model	June 15, 2023
A Cutting Blade for Solder-framed Pins (管腳側面上錫框架產品的切割刀片)	PRC	CN202321131390.7	Company	Utility Model	May 11, 2023
A Process Method for Exposure Alignment in Multi-layer High-density Packaging (一種多層高密度封裝中曝光對位的工藝方法)	PRC	CN202311009444.7	Company	Invention Patent	August 11, 2023
A Chip Pickup Head and Adapted Mounting Base and Installation Device (一種吸片頭及適配的安裝座、安裝裝置)	PRC	CN202320994667.2	Company	Utility Model	April 27, 2023
A Wafer Fixing Carrier (一種晶圓固定載具)	PRC	CN202321268159.2	Company	Utility Model	May 24, 2023
A Pusher Foolproof Mechanism for Punching Mold (一種沖切模具推桿防呆機構)	PRC	CN202320994633.3	Company	Utility Model	April 27, 2023

Patent	Place of Registration	Application Number	Owner	Type	Application Date
A Shaped Heat Dissipation Cap and Semiconductor Packaging Structure Using the Cap (一種異形散熱蓋及使用異形散熱蓋的半導體封裝結構)	PRC	CN202320881740.5	Company	Utility Model	April 19, 2023
An Automatic Optical Inspection Pad Width Adjustment Device (自動光學檢測墊塊寬度調節裝置)	PRC	CN202320319353.2	Company	Utility Model	February 24, 2023
A Chip Protection Packaging Structure (一種芯片保護封裝結構)	PRC	CN202320326250.9	Company	Utility Model	February 27, 2023
A QFN Packaging Structure Reducing Heat Conduction to PCB and Its Preparation Method (一種減少對PCB板熱傳導的QFN封裝結構及其製備方法)	PRC	CN202310432274.7	Company	Invention Patent	April 21, 2023
A QR Code Reading Device Suitable for Semiconductor Packaging (適用於半導體封裝的二維碼讀取裝置)	PRC	CN202320921973.3	Company	Utility Model	April 23, 2023
A Substrate Structure Reducing Overflow (一種減少溢料的基板結構)	PRC	CN202320409274.0	Company	Utility Model	March 02, 2023
A Packaging Structure Optimizing Film Coverage of Filter Products (一種能夠優化濾波器產品覆膜效果的封裝結構)	PRC	CN202320701933.8	Company	Utility Model	April 03, 2023
A Wafer-level Fan-out Packaging Structure Using Silicon-based Support and Its Preparation Method (使用矽基支撐結構的晶圓級扇出型封裝結構及其製備方法)	PRC	CN202310433234.4	Company	Invention Patent	April 21, 2023
A Rework Method for Wafer-level Packaging (一種晶圓級封裝的再處理方法)	PRC	CN202310431692.4	Company	Invention Patent	April 21, 2023

Patent	Place of Registration	Application Number	Owner	Type	Application Date
An Automatic Electroplating Solution Titration Device (電鍍液自動滴定裝置)	PRC	CN202223606117.3	Company	Utility Model	December 31, 2022
A Sandwich-type Packaging Structure for High-pressure Flip-chip (一種耐高壓倒裝芯片的三明治型封裝結構)	PRC	CN202320223721.3	Company	Utility Model	February 15, 2023
A Universal Metal Nozzle Structure for Flip-chip Machines (通用的倒裝機的金屬吸嘴結構)	PRC	CN202320859392.1	Company	Utility Model	April 18, 2023
A Method for Automatically Identifying and Removing Excess Solder Balls on Wafer Maps (一種自動識別晶圓圖紙上多餘錫球及去除多餘錫球的方法)	PRC	CN202310410906.X	Company	Invention Patent	April 18, 2023
A Wafer Testing Device and Its Testing System (一種測試晶圓及其測試系統)	PRC	CN202223520092.5	Company	Utility Model	December 28, 2022
A Chip Peeling Negative Pressure Heating Platform (芯片剝離負壓加熱平台)	PRC	CN202223600004.2	Company	Utility Model	December 30, 2022
A Chip Conductive Pillar (芯片導電柱)	PRC	CN202223400104.0	Company	Utility Model	December 16, 2022
A Coated Multi-metal Conductive Bump Structure (包覆型多金屬導電凸塊結構)	PRC	CN202221949012.5	Company	Utility Model	July 26, 2022
A Wafer Cutting Blade (晶圓切割刀片)	PRC	CN202223111526.6	Company	Utility Model	November 22, 2022
An Electroplating Machine Connection Wire Joint (電鍍機連接線接頭)	PRC	CN202223197621.2	Company	Utility Model	November 30, 2022
A Blocking-type Wide-mouth Dispensing Valve (一種阻斷式寬口點膠閥)	PRC	CN202223112230.6	Company	Utility Model	November 23, 2022
A Packaging Structure of a Filter Module (濾波器模組的封裝結構)	PRC	CN202222463835.3	Company	Utility Model	September 15, 2022
A Device Improving Post-packaging Product Warpage (一種封裝後線改善產品翹曲的裝置)	PRC	CN202222513767.7	Company	Utility Model	September 22, 2022

Patent	Place of Registration	Application Number	Owner	Type	Application Date
A Vacuum Suction Jig Preventing Post-packaging Warpage in Reflow Process (一種封裝後線回流防翹曲真空吸附治具)	PRC	CN202222583938.3	Company	Utility Model	September 28, 2022
A Wafer Flip Device (晶圓倒片裝置)	PRC	CN202222848908.0	Company	Utility Model	October 27, 2022
A Fully Automatic Mesh Plate Cleaning Machine (全自動網板清洗機)	PRC	CN202222446928.5	Company	Utility Model	September 15, 2022
A Mold Flow Balancing Structure for Semiconductor Plastic Encapsulation Molds (半導體塑封模具的模流平衡結構)	PRC	CN202222479551.3	Company	Utility Model	September 19, 2022
A Device Preventing Post-packaging Warpage in Reflow Process (一種封裝後線回流防翹曲裝置)	PRC	CN202221986949.X	Company	Utility Model	July 29, 2022
A Foolproof Device Automatically Adjusting Product Position (自動調整產品位置的防呆裝置)	PRC	CN202222656709.X	Company	Utility Model	October 09, 2022
An Integrated Circuit Chip Packaging Structure (集成電路芯片封裝結構)	PRC	CN202222504241.2	Company	Utility Model	September 21, 2022
A Ball-loading Cleaning Device (一種植球裝載清潔裝置)	PRC	CN202222159352.4	Company	Utility Model	August 16, 2022
A Chip Packaging Method and Structure with High-density Interconnection Layer (一種具有高密度連接層的芯片封裝方法及其芯片封裝結構)	PRC	CN202211179108.2	Company	Invention Patent	September 27, 2022
A Flip-chip Packaging Structure (倒裝芯片封裝結構)	PRC	CN202222063451.2	Company	Utility Model	August 05, 2022
A Multi-turn Groove Frame Preventing Delamination and Its Chip Packaging Structure (一種可實現防止分層的多圈凹槽框架及其芯片封裝結構)	PRC	CN202221011731.2	Company	Utility Model	April 28, 2022

Patent	Place of Registration	Application Number	Owner	Type	Application Date
A Random Sampling Foolproof Device (一種抽檢防呆裝置)	PRC	CN202221958896.0	Company	Utility Model	July 27, 2022
A System Preventing Reverse Material Box Clamping (一種可防反料盒夾取系統)	PRC	CN202123287634.4	Company	Utility Model	December 24, 2021
A Fully Automatic Backside Adhesive Wafer Cleaning Device (一種背膠全自動擦片設備)	PRC	CN202222197408.5	Company	Utility Model	August 19, 2022
A Fully Automatic Solder Ball and Flux Feeding Cabinet (全自動錫球焊劑供料櫃)	PRC	CN202221613513.6	Company	Utility Model	June 23, 2022
A Wafer Marking Printing Auxiliary Jig (一種晶圓刻號打印輔助治具)	PRC	CN202221950431.0	Company	Utility Model	July 27, 2022
A Wafer-level Chip Packaging Structure with Enhanced Adhesion (一種增強結合力的晶圓級芯片封裝結構)	PRC	CN202221511859.5	Company	Utility Model	June 16, 2022
A Fully Automatic Random Sampling Device (一種全自動抽檢器)	PRC	CN202221524956.8	Company	Utility Model	June 17, 2022
A Foolproof Accessory (一種防呆配件)	PRC	CN202221943994.7	Company	Utility Model	July 26, 2022
A Contact-sensing Type Placement Machine Pad Structure (一種接觸感應式貼片機墊塊結構)	PRC	CN202221210823.3	Company	Utility Model	May 18, 2022
A Chip Packaging Structure Increasing Heat Dissipation and Electromagnetic Shielding (一種增加散熱提升電磁屏蔽的芯片封裝結構)	PRC	CN202221608099.X	Company	Utility Model	June 24, 2022
A Packaging Frame Reducing Cross-line Spacing for Wire Bonding (一種可減少跨線增大打線空間的封裝框架)	PRC	CN202221488597.5	Company	Utility Model	June 14, 2022
A Packaging Substrate Structure (一種封裝基板結構)	PRC	CN202221530359.6	Company	Utility Model	June 17, 2022

Patent	Place of Registration	Application Number	Owner	Type	Application Date
A QFN Packaging Structure Fixing Device (一種QFN封裝結構的固定裝置)	PRC	CN202220386403.4	Company	Utility Model	February 24, 2022
A Chip Packaging Structure (芯片封裝結構)	PRC	CN202222145491.1	Company	Utility Model	August 16, 2022
A Flip-chip Packaging Structure (一種倒裝芯片封裝結構)	PRC	CN202221235259.0	Company	Utility Model	May 20, 2022
A Semiconductor Packaging Structure (半導體封裝結構)	PRC	CN202222091385.X	Company	Utility Model	August 10, 2022
A Defective-product-safe Removal Device (一種可實現次品安全去除的檢驗去次機構)	PRC	CN202221016034.6	Company	Utility Model	April 28, 2022
A Chip Packaging Structure Improving Bump and Redistribution Layer Uniformity (一種提高凸塊及再佈線層均匀性的芯片封裝結構)	PRC	CN202220876408.5	Company	Utility Model	April 15, 2022
A Lead Frame with Solid Cutting Tie Bars (一種包含實體切割連筋的引線框架)	PRC	CN202221013025.1	Company	Utility Model	April 27, 2022
A Package Structure without Island Frame (一種無基島框架的封裝結構)	PRC	CN202221004919.4	Company	Utility Model	April 27, 2022
A Foolproof Positioning Rack and Cutting Device Including the Rack (一種防遺忘的定位架及包括定位架的切割裝置)	PRC	CN202220677276.3	Company	Utility Model	March 24, 2022
A Wafer-level Chip Size Packaging Inspection and Reel Labeling Device (一種晶圓級晶片尺寸封裝檢驗換卷貼標裝置)	PRC	CN202220550611.3	Company	Utility Model	March 14, 2022
A Double-sided Packaging Structure (一種雙面封裝結構)	PRC	CN202220300421.6	Company	Utility Model	February 15, 2022
A Wafer-level Chip Packaging Structure (一種晶圓級芯片封裝結構)	PRC	CN202220656365.X	Company	Utility Model	March 24, 2022

Patent	Place of Registration	Application Number	Owner	Type	Application Date
A Glue Plate Structure with Filtration Function (一種可實現過濾功能的膠板結構)	PRC	CN202123082033.X	Company	Utility Model	December 09, 2021
A Lead Frame Increasing Pin Spacing (一種增加管腳間隙的引線框架). .	PRC	CN202220474953.1	Company	Utility Model	March 04, 2022
A Multi-chip Filter Packaging Structure (一種多芯片濾波器封裝結構).	PRC	CN202123310071.6	Company	Utility Model	December 27, 2021
A Six-side Coated Fan-out Chip Packaging Structure (一種六面包覆的扇出型芯片封裝結構).	PRC	CN202123440565.6	Company	Invention Patent	December 31, 2021
A Multi-chip Filter Packaging Structure Based on Adapter Board (一種基於轉接板的多芯片濾波器封裝結構).	PRC	CN202123310060.8	Company	Utility Model	December 27, 2021
A Chip Packaging Structure Preventing Indium Sputtering (一種防止銦片濺射的芯片封裝結構)	PRC	CN202123391212.1	Company	Utility Model	December 31, 2021
An Automatic Liquid Supply and Gas-liquid Separation Reflow System (自動供液氣液分離藥液回流系統) . . .	PRC	CN202123218365.6	Company	Utility Model	December 20, 2021
A Semiconductor Device and Testing System (一種半導體器件及測試系統).	PRC	CN202123125358.1	Company	Utility Model	December 13, 2021
A Semiconductor Packaging Structure and Testing System (一種半導體封裝結構及測試系統).	PRC	CN202123170489.1	Company	Utility Model	December 13, 2021
A Chip Plastic Encapsulation Mold (一種芯片塑封模具)	PRC	CN202122843347.0	Company	Utility Model	November 18, 2021
A Semiconductor Wet-process Equipment Multi-material Mixing Centralized Liquid Supply System (半導體濕法設備混合配比集中供液系統)	PRC	CN202122822174.4	Company	Utility Model	November 17, 2021

Patent	Place of Registration	Application Number	Owner	Type	Application Date
A Lead Frame Structure (一種引線框架結構)	PRC	CN202122866577.9	Company	Utility Model	November 22, 2021
A Chip Packaging Structure with Electromagnetic Shielding (一種帶有電磁屏蔽的芯片封裝結構)	PRC	CN202122586612.1	Company	Utility Model	October 26, 2021
A High-density Fan-out Packaging Structure (一種高密度扇出封裝結構)	PRC	CN202220326220.3	Company	Utility Model	February 18, 2022
A Fan-out Packaging Method and Fan-out Packaging Structure (一種扇出封裝方法及扇出封裝結構)	PRC	CN202111352295.5	Company	Utility Model	November 16, 2021
A Multi-chip Filter Packaging Structure Based on Barrier Layer (一種基於阻隔層的多芯片濾波器封裝結構)	PRC	CN202123314330.2	Company	Utility Model	December 27, 2021
A Wafer Coating Hotplate Transfer Teaching Auxiliary Jig (晶圓塗膠熱板傳送示教輔助治具)	PRC	CN202122367486.0	Company	Utility Model	September 28, 2021

3. FURTHER INFORMATION ABOUT OUR DIRECTORS AND SUPERVISOR

Particulars of Directors' and Supervisor's Contracts and Appointment Letters

We have entered into a contract with each of our Directors and Supervisor in respect of, among other things, (i) the term of office, and (ii) termination provisions. Save as disclosed above, none of our Directors or Supervisor has or is proposed to enter into a service contract with any member of our Company other than contracts expiring or determinable by the relevant employer within one year without the payment of compensation (other than statutory compensation).

Remuneration of Directors, Supervisor and Senior Management

Save as disclosed in the section headed "Directors, Supervisor and Senior Management — Remuneration of Directors, Supervisor and Senior Management" in this document, none of our Directors or Supervisor received other remuneration from our Company for each of the three years ended December 31, 2025.

Agency Fees or Commissions Received

The [**REDACTED**] will receive an [**REDACTED**] in connection with the [**REDACTED**], as detailed in "[**REDACTED**] — [**REDACTED**] and Expenses". Save in connection with the [**REDACTED**], no commissions, discounts, brokerages or other special terms have been granted by our Group to any person (including the Directors, promoters and experts referred to in "— Other

Information — Qualifications and Consents of Experts" below) in connection with the issue or sale of any capital or security of our Company or any member of our Group within the two years immediately preceding the date of this Document.

Within the two years immediately preceding the date of this document, no commission has been paid or is payable for subscription, agreeing to subscribe, procuring subscription or agreeing to procure subscription for any share in or debentures of our Company.

Disclosure of Interests of Directors

Immediately following the completion of the [**REDACTED**] assuming that the [**REDACTED**] is not exercised and without taking into account any Shares to be [**REDACTED**] upon the exercise of any options granted under the [**REDACTED**] Share — Option Scheme, none of our Directors have any interest and/or short position in the Shares, underlying Shares and debentures of our Company or our associated corporations (within the meaning of Part XV of the SFO) which will be required to be notified to our Company and the Stock Exchange pursuant to Divisions 7 and 8 of Part XV of the SFO (including interest or short position which they were taken or deemed to have under such provisions of the SFO) or which will be required, pursuant to section 352 of the SFO, to be entered in the register referred to therein, or which will be required, pursuant to the Model Code for Securities Transactions by Directors of Listed Issuers as set out in Appendix C3 to the Listing Rules to be notified to our Company, once the [**REDACTED**] are [**REDACTED**] on the Stock Exchange.

			As of the Latest Practicable Date and immediately prior to the completion of the [REDACTED]		Immediately after the completion of the [REDACTED] (assuming the [REDACTED] is not exercised and without taking into account any Shares to be [REDACTED] upon the exercise of any options granted under the [REDACTED] Share Option Scheme)		
Name	**Positions**	**Nature of Interest**	**Number and description of Shares**	**Approximate percentage of interest in our Company**	**Number and description of Shares**	**Approximate percentage of interest in our Company[8]**	**Approximate percentage of [REDACTED] (as appropriate)[8]**
Mr. Zhang Guodong .	Chairman of the Board, Executive Director	Beneficial owner[1]; interest in controlled corporations[4][5]; parties acting in concert[6]	239,240,000 Unlisted Shares	24.95%	[REDACTED]	[REDACTED]	[REDACTED]
Mr. Pan Mingdong. .	Executive Director	Beneficial owner[2]; interest in controlled corporations[4][5]; parties acting in concert[6]	239,240,000 Unlisted Shares	24.95%	[REDACTED]	[REDACTED]	[REDACTED]
Mr. Liu Yi	Executive Director	Beneficial owner[3]; interest in controlled corporations[4][5]; parties acting in concert[6]	239,240,000 Unlisted Shares	24.95%	[REDACTED]	[REDACTED]	[REDACTED]

Notes:

(1) As of the Latest Practicable Date, Mr. Zhang Guodong was directly interested in approximately 5.38% of the equity interest in our Company;

(2) As of the Latest Practicable Date, Mr. Pan Mingdong was directly interested in approximately 3.01% of the equity interest in our Company;

(3) As of the Latest Practicable Date, Mr. Liu Yi was directly interested in approximately 1.04% of the equity interest in our Company;

(4) As of the Latest Practicable Date, Nanjing Ningtaixin Enterprise Consulting Management Partnership (Limited Partnership)* (南京寧泰芯企業諮詢管理合夥企業(有限合夥)) ("**Ningtaixin**") was directly interested in approximately 9.49% of the equity interest in our Company. Pursuant to a limited partnership agreement governing Ningtaixin, Mr. Zhang Guodong was the general partner of Ningtaixin. As the general partner of Ningtaixin, Mr. Zhang Guodong was deemed to have *de facto* control in Ningtaixin and hence was the controller of Ningtaixin. Accordingly, Mr. Zhang Guodong is deemed to be interested in such Shares held by Ningtaixin for the purpose of the SFO;

(5) As of the Latest Practicable Date, Ningbo Meishan Bonded Port Area Ningpuxin Enterprise Management Partnership (Limited Partnership)* (寧波梅山保税港區寧浦芯企業管理合夥企業(有限合夥)) ("**Ningpuxin**") was directly interested in approximately 6.02% of the equity interest in our Company. Pursuant to a limited partnership agreement governing Ningpuxin, Mr. Zhang Guodong was the general partner of Ningpuxin. As the general partner of Ningpuxin, Mr. Zhang Guodong was deemed to have *de facto* control in Ningpuxin and hence was the controller of Ningpuxin. Accordingly, Mr. Zhang Guodong is deemed to be interested in such Shares held by Ningpuxin for the purpose of the SFO;

(6) Pursuant to the concert party agreement dated June 8, 2023 entered into by and between Mr. Zhang Guodong, Mr. Pan Mingdong, Mr. Liu Yi, Ningtaixin and Ningpuxin, the parties acknowledged that (i) they shall consult each other in respect of the decision making relating to the business operation and corporate governance of the Company and reach consensus before voting unanimously at the general meetings or board meetings of the Company, and (ii) where consensus cannot be reached between the parties, parties shall follow the instruction of Mr. Zhang Guodong. As a result, Mr. Zhang Guodong, Mr. Pan Mingdong, Mr. Liu Yi, Ningtaixin and Ningpuxin held in aggregate approximately 24.95% of the issued share capital of our Company, and are parties acting in concert. They are also considered the Single Largest Group of Shareholders of our Company; and

(7) The calculation is based on the assumption that (i) [**REDACTED**] will be [**REDACTED**] into H Shares; (ii) the [**REDACTED**] is not exercised; (iii) without taking into account any Shares to be issued upon the exercise of any options granted under the [**REDACTED**] Share Option Scheme; and (iv) total number of Shares in issue immediately upon completion of the [**REDACTED**] will be [**REDACTED**] Shares.

Save as disclosed in "Substantial Shareholders" in this document, our Directors are not aware of any other person who will, immediately following the completion of the [**REDACTED**] and the [**REDACTED**] of the [**REDACTED**] into H Shares, have an interest and/or short position in the Shares or underlying Shares which are required to be disclosed to our Company and the Stock Exchange under the provisions of Divisions 2 and 3 of Part XV of the SFO, or, directly or indirectly, be interested in 10% or more of the nominal value of any class of share capital carrying the rights to vote in all circumstances at the general meetings of our Company or any other members of our Company.

Disclosure of Interests of Substantial Shareholders

For information on the persons who will, immediately following the completion of the [**REDACTED**], have interests or short positions in our Shares or underlying Shares which would be required to be disclosed to us and the Stock Exchange under the provisions of Divisions 2 and 3 of Part XV of the SFO, see the section headed "Substantial Shareholders".

Interests of substantial shareholder in non wholly-owned subsidiary of our Company

Our subsidiary	Registered capital	Party with 10% or more equity interest (other than members of the Group)	Approximate percentage of shareholding
Yangzhou Chiplet. . .	RMB820 million	Yangzhou Longtou Semiconductor Industry Investment Fund Partnership (Limited Partnership)* (揚州龍投芯粒半導體產業投資基金合夥企業(有限合夥))	71.95%

So far as set out above, our Directors are not aware of any persons (other than our Directors or Supervisors) who will, immediately following the completion of the [**REDACTED**], directly or indirectly, be interested in 10% or more of the nominal value of any class of share capital carrying rights to vote in all circumstances at general meetings of any other member of our Group.

4. OTHER INFORMATION

[REDACTED] Share Option Scheme

Our Company adopted a [**REDACTED**] Share Option Scheme which was approved by the Shareholders on October 13, 2025. Pursuant to the [**REDACTED**] Share Option Scheme, up to [**REDACTED**] share options may be granted to eligible participants before [**REDACTED**], representing [**REDACTED**]% of the total share capital of our Company immediately prior to the [**REDACTED**]. The share options will be settled by the issue of H shares of the Company upon exercise, subject to compliance with the relevant requirements under the Listing Rules. The following is a summary of the principal terms of the [**REDACTED**] Share Option Scheme:

Purpose

The purposes of the [**REDACTED**] Share Option Scheme are to further improve our Company's long-term incentive mechanism, attract and retain outstanding talents, fully motivate directors, senior management, key management personnel, and core technical or business staff, effectively align the interests of shareholders, our Company, and the core team, and promote the sustainable development of our Company in accordance with the principle of "returns commensurate with contributions."

Eligible Participants

Persons eligible to participate in the [**REDACTED**] Share Option Scheme (the "**Participants**") include directors, senior and key management personnel, core technical and business staff, and other employees who have made or are expected to make significant contributions to the growth and development of our Company, as well as other employees deemed necessary by the Board to be included in the [**REDACTED**] Share Option Scheme. A total of 38 Participants are involved in the [**REDACTED**] Share Option Scheme.

Administration

The approval, alteration and termination of the [**REDACTED**] Share Option Scheme are subject to the Shareholders' meeting. Our Board is authorized for the implementation of the [**REDACTED**] Share Option Scheme.

Exercise Price

The exercise price of the share options is RMB[**REDACTED**], which is not lower than the audited net asset value per share of the Company as of December 31, 2024. The exercise price will be adjusted in the event of capitalization issue, bonus issue, subdivision, consolidation, rights issue, or dividend distribution.

Vesting and Exercise Period

The [**REDACTED**] Share Option Scheme is valid for 60 months from the date of registration of the grant until all granted options have been exercised or canceled. Unexercised options will lapse automatically upon expiry of the exercise period.

The share options granted under the [**REDACTED**] Share Option Scheme are subject to a lock-up period of 24 months from the grant date and may be exercised in three tranches. Specifically, 30% of the options shall become exercisable from the 24th to the 36th month following the registration of the grant; 40% of the options shall become exercisable from the 36th to the 48th month; and the remaining 30% of the options shall become exercisable from the 48th to the 60th month following the registration of the grant.

Lapse

In the event of resignation, dismissal, retirement, incompetence, or breach of relevant obligations by a Participant, all Awards granted to such Participant that remain unexercised shall immediately cease to be exercisable and shall be canceled by the Company.

Details of the Options to be Granted

In November 2025, an aggregate of [**REDACTED**] share options have been granted to 38 Participants under the Scheme, representing [**REDACTED**]% of the total issued share capital of our Company immediately after the [**REDACTED**].

Details of the share options to be granted before [**REDACTED**] under the [**REDACTED**] Share Option Scheme are set out as followed:

Name	Address	Exercise Price per Share	Number of Shares underlying the outstanding options	Approximate % of issued shares immediately after completion of the [REDACTED]
		(RMB)		
Senior Management				
Ms. Fang Yaping (方亞萍)	Room 102, No. 66 Longxi Garden, Shishan Road, Jiangyin City, Jiangsu Province, PRC	[**REDACTED**]	[**REDACTED**]	[**REDACTED**]
Subtotal			[**REDACTED**]	[**REDACTED**]
Other core management and key technical staff				
Subtotal			[**REDACTED**]	[**REDACTED**]
Total outstanding share options			[**REDACTED**]	[**REDACTED**]

Estate Duty

Our Directors have been advised that no material liability for estate duty is likely to fall on our Company or any member of our Group under the laws of the PRC.

Litigation

Save as disclosed above, as of the Latest Practicable Date, no member of our Group was engaged in any litigation or arbitration of material importance and, so far as our Directors are aware, no litigation or claim of material importance is pending or threatened by or against any member of our Group.

Sole Sponsor

The Sole Sponsor has made an [**REDACTED**] on our behalf to the [**REDACTED**] of the Stock Exchange for a [**REDACTED**] of, and permission to [**REDACTED**] in, all the [**REDACTED**] to be [**REDACTED**] as mentioned in this Document. The Sole Sponsor satisfies the independence criteria applicable to sponsors set out in Rule 3A.07 of the Listing Rules.

Pursuant to the engagement letter entered into between our Company and the Sole Sponsor, we have agreed to pay the Sole Sponsor a fee of USD0.6 million to act as the sponsor of our Company in connection with the proposed [**REDACTED**] on the Stock Exchange.

Compliance Advisor

Our Company has appointed Quam Capital Limited as its Compliance Advisor upon [**REDACTED**] in compliance with Rule 3A.19 of the Listing Rules.

Preliminary Expenses

Our Company did not incur material preliminary expense as of the Latest Practicable Date.

Promoters

The promoters of our Company are Xinlianxin, Nanjing Yuanjun and Ningtaixin. For details of the promoters of our Company, see "History, Development and Corporate Structure" in this Document.

Save for the [**REDACTED**] and as disclosed in this document, within the two years immediately preceding the date of this document, no cash, securities, amount or benefit has been paid, allotted or given, or has been proposed to be paid, allotted or given, to any of the promoters named above in connection with the [**REDACTED**] or the related transactions described in this Document.

Qualifications of Experts

The qualifications of the experts which have given opinions or advice which are contained in, or referred to in, this document are as follows:

Name of Expert	Qualifications
Huatai Financial Holdings (Hong Kong) Limited	A licensed corporation to conduct Type 1 (dealing in securities), Type 2 (dealing in futures contracts), Type 3 (leveraged foreign exchange trading), Type 4 (advising on securities), Type 6 (advising on corporate finance), Type 7 (providing automated trading services) and Type 9 (asset management) regulated activities under the SFO
Ernst & Young	Certified Public Accountants and Registered Public Interest Entity Auditor
Jiangsu C&T Partners Law Firm	Legal advisors to our Company as to PRC laws
Frost & Sullivan (Beijing) Inc., Shanghai Branch Co.	Independent industry consultant
Eversheds Sutherland	Legal advisors to our Company as to International Sanctions and Export Control laws

Consents of experts

Each of the experts as referred to in the paragraph headed "— 4. Other Information — Qualification of Experts" in this appendix has given and has not withdrawn their respective written consents to the issue of this document with the inclusion of their reports and/or letters the references to its name included herein in the form and context in which it is respectively included.

None of the experts named above has any shareholding interests in any member of our Company or the right (whether legally enforceable or not) to subscribe for or to nominate persons to subscribe for securities in any member of our Company.

Binding Effect

This document shall have the effect, if an application is made in pursuance hereof, of rendering all persons concerned bound by all of the provisions (other than the penal provisions) of Sections 44A and 44B of the Companies (Winding Up and Miscellaneous Provisions) Ordinance so far as applicable.

Bilingual Document

The English language and Chinese language versions of this document are being published separately, in reliance upon the exemption provided in Section 4 of the Companies (Exemption of Companies and Prospectuses from Compliance with Provisions) Notice (Chapter 32L of the Laws of Hong Kong).

No Material Adverse Change

Our Directors confirm that, up to the date of this document, there has been no material adverse change in the financial or trading position or prospect of our Group since December 31, 2025 (being the date to which the latest consolidated financial statements of our Group were prepared).

Taxation of holders of H Shares

The sale, purchase and transfer of H Shares registered with our Hong Kong branch register of members will be subject to Hong Kong stamp duty. The current rate charged on each of the purchaser and seller is 0.1% of the consideration of or, if higher, of the fair value of our Shares being sold or transferred. For further details in relation to taxation, see Appendix III to this document.

Miscellaneous

(i) Save as disclosed in "History, Development and Corporate Structure", within the two years preceding the date of this document, no share or loan capital of our Company or any of its subsidiary has been issued or has been agreed to be issued fully or partly paid either for cash or for a consideration other than cash;

(ii) No share or loan capital of our Company, if any, is under option or is agreed conditionally or unconditionally to be put under option;

(iii) No founder, management or deferred shares of our Company or any of its subsidiary have been issued or have been agreed to be issued;

(iv) Our Company is not presently listed on any stock exchange or traded on any trading system;

(v) Our Company has no outstanding convertible debt securities or debentures;

(vi) None of the experts listed under "— Qualifications of Experts" in this section is interested beneficially or non-beneficially in any shares in any member of our Group or has any right or option (whether legally enforceable or not) to subscribe for or to nominate persons to subscribe for securities in any member of our Group save in connection with the [**REDACTED**];

(vii) The English text of this document shall prevail over their respective Chinese text;

(viii) There has not been any interruption in the business of our Group which may have or has had a significant effect on the financial position of our Group in the 12 months preceding the date of this document; and

(ix) There is no arrangement under which future dividends are waived or agreed to be waived.